

High-speed diode

FEATURES

- Ultra small plastic SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA.

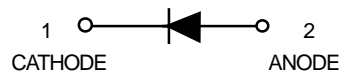
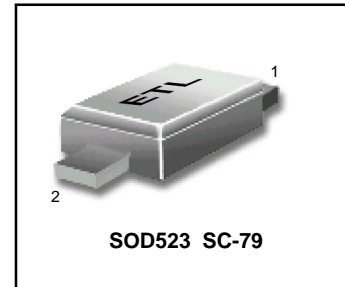
APPLICATIONS

- High-speed switching in e.g. surface mounted circuits.

DESCRIPTION

The BAS516 is a high-speed switching diode fabricated in planar technology, and encapsulated in the SOD523 (SC79) SMD plastic package.

BAS516



LIMITING VALUES In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	85	V
V_R	continuous reverse voltage		–	75	V
I_F	continuous forward current	$T_s=90^{\circ}\text{C}$; note 1; see Fig.1	–	250	mA
I_{FRM}	repetitive peak forward current		–	500	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j=25^{\circ}\text{C}$ prior to surge; see Fig.3			
		$t=1\mu\text{s}$	–	4	A
		$t=1\text{ ms}$	–	1	A
		$t=1\text{ s}$	–	0.5	A
P_{tot}	total power dissipation	$T_s=90^{\circ}\text{C}$; note 1	–	500	mW
T_{stg}	storage temperature		-65	+150	$^{\circ}\text{C}$
T_j	junction temperature		–	150	$^{\circ}\text{C}$

Note

1. T_s is the temperature at the soldering point of the cathode tab.

ELECTRICAL CHARACTERISTICS $T_j=25^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_F	forward voltage	see Fig.2 $I_F=1\text{ mA}$	715	mV
		$I_F=10\text{ mA}$	855	mV
		$I_F=50\text{ mA}$	1	V
		$I_F=150\text{ mA}$	1.25	V
I_R	reverse current	see Fig.4 $V_R=25\text{ V}$	30	nA
		$V_R=75\text{ V}$	1	μA
		$V_R=25\text{ V}; T_j=150^{\circ}\text{C}$	30	μA
		$V_R=75\text{ V}; T_j=150^{\circ}\text{C}$;	50	μA
C_d	diode capacitance	$f=1\text{ MHz}; V_R=0$; see Fig.5	1	pF
t_{rr}	reverse recovery time	when switched from $I_F=10\text{ mA}$ to $I_R=10\text{ mA}$; $R_L=100\Omega$; measured at $I_R=1\text{ mA}$; see Fig.6	4	ns
V_{fr}	forward recovery voltage	when switched from $I_F=10\text{ mA}$; $t_r=20\text{ ns}$; see Fig.7	1.75	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R_{thj-s}	thermal resistance from junction to soldering point	note 1	120	K/W

Note 1. Soldering point of the cathode tab.

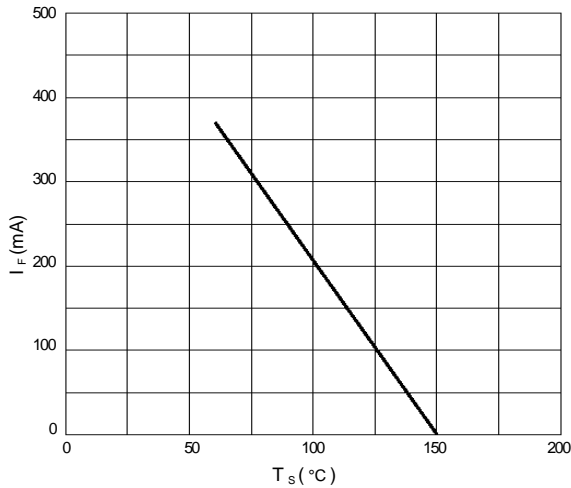


Fig.1 Maximum permissible continuous forward current as a function of soldering point temperature.

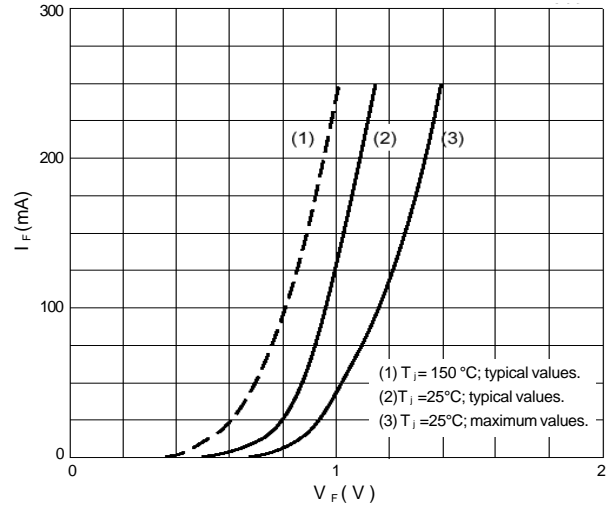


Fig.2 Forward current as a function of forward voltage.

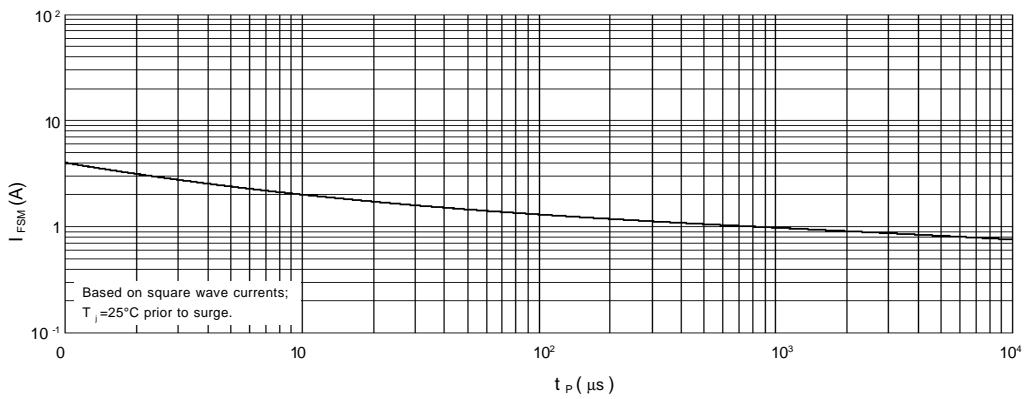


Fig.3 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

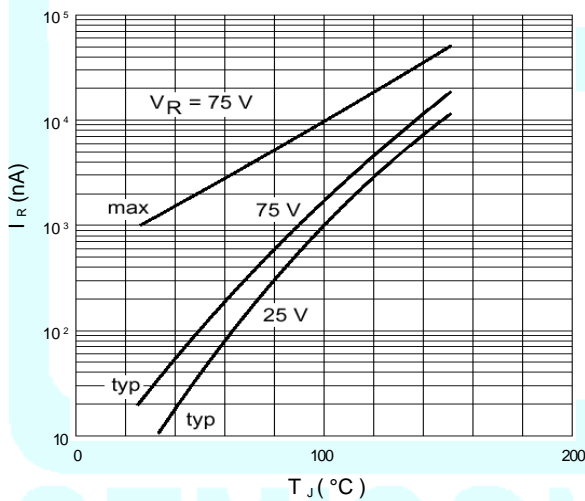


Fig.4 Reverse current as a function of junction temperature.

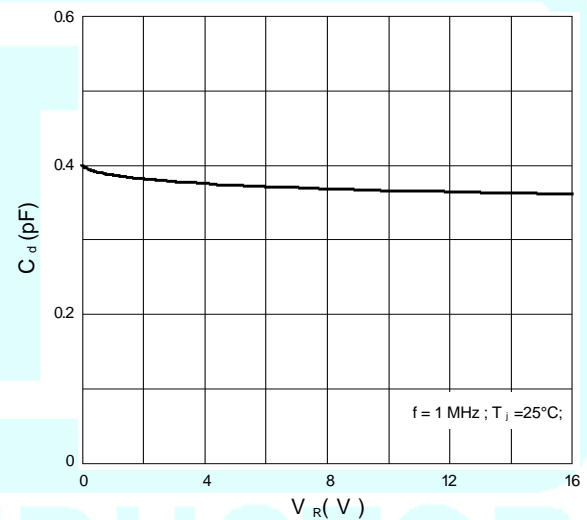
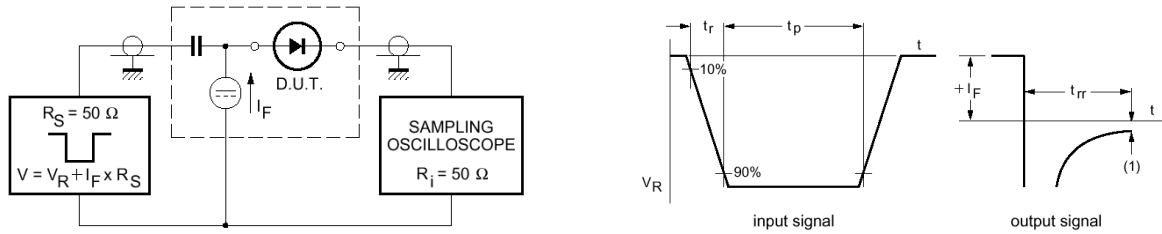
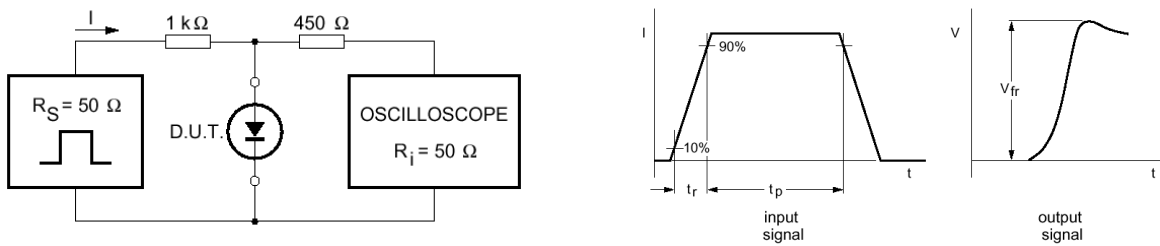


Fig.5 Diode capacitance as a function of reverse voltage; typical values.



(1) $I_R = 1 \text{ mA}$.
 Input signal: reverse pulse rise time $t_r = 0.6 \text{ ns}$; reverse voltage pulse duration $t_p = 100 \text{ ns}$; duty factor $\delta = 0.05$;
 Oscilloscope: rise time $t_s = 0.35 \text{ ns}$.

Fig.6 Reverse recovery voltage test circuit and waveforms.



Input signal: forward pulse rise time $t_r = 20 \text{ ns}$; forward current pulse duration $t_p \geq 100 \text{ ns}$; duty factor $\delta \leq 0.005$.

Fig.7 Forward recovery voltage test circuit and waveforms.